EPO-TEK® 353ND-T4

Technical Data Sheet
For Reference Only
Thixotropic Epoxy

Date:	February 2021	
Rev:	XI	
No. of Components:	Two	
Mix Ratio by Weight:	10 : 1	
Specific Gravity:	Part A: 1.11	Part B: 1.02
Pot Life:	3 Hours	
Shelf Life- Bulk:	Nine months refrigerated	

Recommended Cure: 150°C / 1 Hour

Minimum Alternative Cure(s):
May not achieve performance properties listed below
150°C / 1 Minute
120°C / 5 Minutes
100°C / 10 Minutes

NOTES:
- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.

Product Description: EPO-TEK® 353ND-T4 is a two component, highly thixotropic epoxy with non-flowing properties and high temperature resistance. This is a higher viscosity version of EPO-TEK® 353ND-T for applications needing decreased flow.

Typical Properties: Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results. Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:		
* Color (before cure):	Part A: Tan	Part B: Amber
* Consistency:	Smooth thixotropic paste	
* Viscosity (23°C) @ 20 rpm:	11,000-17,000	cPs
Thixotropic Index:	2.3	
* Glass Transition Temp:	≥ 90	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):		
Below Tg:	43	x 10^{-6} in/in°C
Above Tg:	231	x 10^{-6} in/in°C
Shore D Hardness:	80	
Lap Shear @ 23°C:	> 2,000	psi
Die Shear @ 23°C:	≥ 15	Kg 5,334 psi
Degradation Temp:	409	°C
Weight Loss:		
@ 200°C:	0.53	%
@ 250°C:	1.22	%
@ 300°C:	2.37	%
Suggested Operating Temperature:	< 325	°C (Intermittent)
Storage Modulus:	559,120	psi
* Particle Size:	≤ 20	microns

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity:	N/A	
Volume Resistivity @ 23°C:	≥ 4 x 10^{12}	Ohm-cm
Dielectric Constant (1KHz):	3.21	
Dissipation Factor (1KHz):	0.003	

EPOXY TECHNOLOGY, INC.
14 FORTUNE DRIVE, BILLERICA, MA 01821 (978) 667-3805, FAX (978) 663-9782
www.epotek.com
A Meridian Adhesives Group Company

EPO-TEK® 353ND-T4

Technical Data Sheet
For Reference Only
Thixotropic Epoxy

EPO-TEK® 353ND-T4 Advantages & Suggested Application Notes:

- Suitable for fiber optic and circuit assembly applications.
- Recommended for bonding metals, glass, ceramics and many types of plastic.
- High temperature adhesive for hybrids and medical devices; it can resist the 300°C range for long periods of time.
- Used in circuit assembly applications; staking SMD's to PCB, bonding ferrite cores together in copper coil windings, inductor coils and power devices; suitable for COB glob top DAM material.
- Alternative product versions available with distinct viscosity ranges - contact Technical Services at techserv@epotek.com for best recommendation.
- Can be applied by screen printing, spatula, hand held or automatic dispensing equipment.
- Amber color change when properly cured for easy visual ID and inspection.

EPOXY TECHNOLOGY, INC.
14 FORTUNE DRIVE, BILLERICA, MA 01821 (978) 667-3805, FAX (978) 663-9782
www.epotek.com
A Meridian Adhesives Group Company